

March 2002 Revised June 2005

74LCXZ16245

Low Voltage 16-Bit Bidirectional Transceiver with 5V Tolerant Inputs and Outputs

General Description

The LCXZ16245 contains sixteen non-inverting bidirectional buffers with 3-STATE outputs and is intended for bus oriented applications. The device is designed for low voltage (2.7V or 3.3V) $V_{\rm CC}$ applications with capability of interfacing to a 5V signal environment. The device is byte controlled. Each byte has separate control inputs which could be shorted together for full 16-bit operation. The $\overline{T/R}$ inputs determine the direction of data flow through the device. The $\overline{\rm OE}$ inputs disable both the A and B ports by placing them in a high impedance state.

When V_{CC} is between 0V and 1.5V, the LCXZ16245 is on the high impedance state during power-up or power-down. This places the outputs in the high impedance (Z) state preventing intermittent low impedance loading or glitching in bus oriented applications.

The LCXZ16245 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant inputs and outputs
- 2.7V-3.6V V_{CC} specifications provided
- \blacksquare 4.5 ns t_{PD} max (V $_{CC}$ = 3.3V), 20 μA I_{CC} max
- Power-down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- \pm 24 mA output drive ($V_{CC} = 3.0V$)
- Implements patented noise/EMI reduction circuitry
- Latch-up performance conforms to the requirements of JESD78
- ESD performance:

Human body model > 2000V

Machine model > 200V

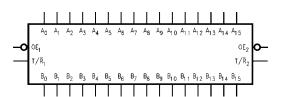
Note 1: To ensure the high-impedance state during power up or down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pull-up resistor: the minimum value or the resistor is determined by the current-sourcing capability of the driver.

Ordering Code:

Order Number	Package Number	Package Description	
74I CXZ16245MTD	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide	

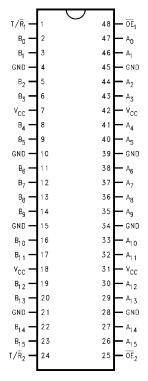
Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code

Logic Symbol



Connection Diagram

Pin Assignment for SSOP and TSSOP



Pin Descriptions

Pin Names	Description
OE n	Output Enable Input
T/R _n Transmit/Receive Input	
A ₀ -A ₁₅ B ₀ -B ₁₅	Side A Inputs or 3-STATE Outputs
B ₀ -B ₁₅	Side B Inputs or 3-STATE Outputs
NC	No Connect

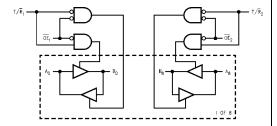
Truth Tables

Ī	Inputs		Outmute	
Ī	OE ₁	T/R ₁	Outputs	
Ī	L	L	Bus B ₀ –B ₇ Data to Bus A ₀ –A ₇	
	L	Н	Bus A ₀ -A ₇ Data to Bus B ₀ -B ₇	
	Н	Χ	HIGH Z State on A ₀ -A ₇ , B ₀ -B ₇	

Inputs		Outroots	
OE ₂	T/R ₂	Outputs	
L	L	Bus B ₈ –B ₁₅ Data to Bus A ₈ –A ₁₅	
L	Н	Bus A ₈ -A ₁₅ Data to Bus B ₈ -B ₁₅	
Н	X	HIGH Z State on A ₈ –A ₁₅ , B ₈ –B ₁₅	

L
H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

Logic Diagram



Absolute Maximum Ratings(Note 2) Symbol Parameter Value Units Conditions ٧ Supply Voltage -0.5 to +7.0 V_{CC} ٧ DC Input Voltage -0.5 to +7.0 V_{I} DC Output Voltage ٧o -0.5 to +7.0 Output in 3-STATE ٧ Output in HIGH or LOW State (Note 3) -0.5 to $V_{CC} + 0.5$ DC Input Diode Current -50 V_I < GND mΑ I_{IK} DC Output Diode Current -50 V_O < GND I_{OK} mΑ +50 $V_O > V_{CC}$ DC Output Source/Sink Current ±50 mΑ I_{O} I_{CC} DC Supply Current per Supply Pin ±100 mΑ DC Ground Current per Ground Pin ±100 I_{GND}

-65 to +150

Recommended Operating Conditions (Note 4)

Symbol	Parameter			Max	Units
V _{CC}	Supply Voltage	Operating	2.7	3.6	V
VI	Input Voltage		0	5.5	V
Vo	Output Voltage	HIGH or LOW State	0	V _{CC}	V
		3-STATE	0	5.5	V
I _{OH} /I _{OL}	Output Current	$V_{CC} = 3.0V - 3.6V$ $V_{CC} = 2.7V - 3.0V$		±24	mA
		$V_{CC} = 2.7V - 3.0V$		±12	IIIA
T _A	Free-Air Operating Temperature		-40	85	°C
Δt/ΔV	Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V		0	10	ns/V

Note 2: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 3: I_O Absolute Maximum Rating must be observed.

Storage Temperature

 T_{STG}

Note 4: Unused inputs or I/O's must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	Conditions	V _{cc}	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		Units
Cy20.		Conditions	(V)	Min	Max	Onno
V _{IH}	HIGH Level Input Voltage		2.7 – 3.6	2.0		V
V _{IL}	LOW Level Input Voltage		2.7 – 3.6		0.8	V
V _{OH}	HIGH Level Output Voltage	I _{OH} = -100 μA	2.7 – 3.6	V _{CC} - 0.2		
		I _{OH} = -12 mA	2.7	2.2		V
		$I_{OH} = -18 \text{ mA}$	3.0	2.4		V
		$I_{OH} = -24 \text{ mA}$	3.0	2.2		
V _{OL}	LOW Level Output Voltage	$I_{OL} = 100 \mu A$	2.7 – 3.6		0.2	
		I _{OL} = 12 mA	2.7		0.4	V
		I _{OL} = 16 mA	3.0		0.4	v
		I _{OL} = 24 mA	3.0		0.55	
l _l	Input Leakage Current	$0 \leq V_I \leq 5.5V$	2.7 – 3.6		±5.0	μА
loz	3-STATE I/O Leakage	$0 \le V_O \le 5.5V$	2.7 – 3.6		±5.0	۸
		$V_I = V_{IH}$ or V_{IL}				μА
l _{OFF}	Power-Off Leakage Current	V_I or $V_O = 5.5V$	0		10	μΑ
I _{PU/PD}	Power-Up/Power-Down	$V_O = 0.5V$ to V_{CC}	0 - 1.5		±5.0	^
	3-STATE Output Current	$V_I = V_{CC}$ or GND	0 - 1.5		±5.0	μА
I _{CC}	Quiescent Supply Current	$V_I = V_{CC}$ or GND	2.7–3.6		225	μА
		$3.6V \le V_I$, $V_O \le 5.5V$ (Note 5)	2.7–3.6		±225	μА
Δl _{CC}	Increase in I _{CC} per Input	V _{IH} = V _{CC} -0.6V	2.7-3.6		500	μΑ

Note 5: Outputs disabled or 3-STATE only.

AC Electrical Characteristics

		$T_A = -40$ °C to $+85$ °C, $R_L = 500\Omega$				
Symbol	Parameter	$V_{CC} = 3.3 V \pm 0.3 V$ $C_L = 50 \ pF$		V _{CC} = 2.7V C _L = 50 pF		Units
t _{PHL}	Propagation Delay	1.0	4.5	1.0	5.2	ns
t _{PLH}	A_n to B_n or B_n to A_n	1.0	4.5	1.0	5.2	
t _{PZL}	Output Enable Time	1.0	6.5	1.0	7.2	
t_{PZH}		1.0	6.5	1.0	7.2	ns
t _{PLZ}	Output Disable Time	1.0	6.4	1.0	6.9	ns
t _{PHZ}		1.0	6.4	1.0	6.9	ns
toshl	Output to Output Skew (Note 6)		1.0			ns
toslh			1.0			115

Note 6: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}). Parameter guaranteed by design.

Dynamic Switching Characteristics

Symbol	Parameter	Conditions	V _{cc}	$T_A = 25^{\circ}C$	Units	
		Conditions	(V)	Typical	O.m.o	
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	8.0	V	
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	$C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$	3.3	-0.8	V	

Capacitance

Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	$V_{CC} = Open, V_I = 0V \text{ or } V_{CC}$	7	pF
C _{I/O}	Input/Output Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC} , $f = 10$ MHz	20	pF

AC LOADING and WAVEFORMS Generic for LCX Family

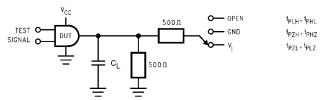
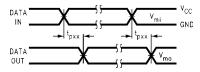
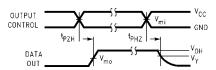


FIGURE 1. AC Test Circuit (C_L includes probe and jig capacitance)

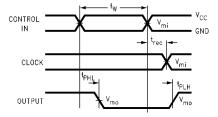
Test	Switch
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6V at V_{CC} = 3.3 \pm 0.3V, and 2.7V
t _{PZH} , t _{PHZ}	GND



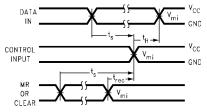
Waveform for Inverting and Non-Inverting Functions



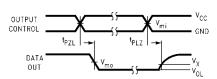
3-STATE Output High Enable and Disable Times for Logic



Propagation Delay. Pulse Width and t_{rec} Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

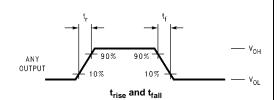
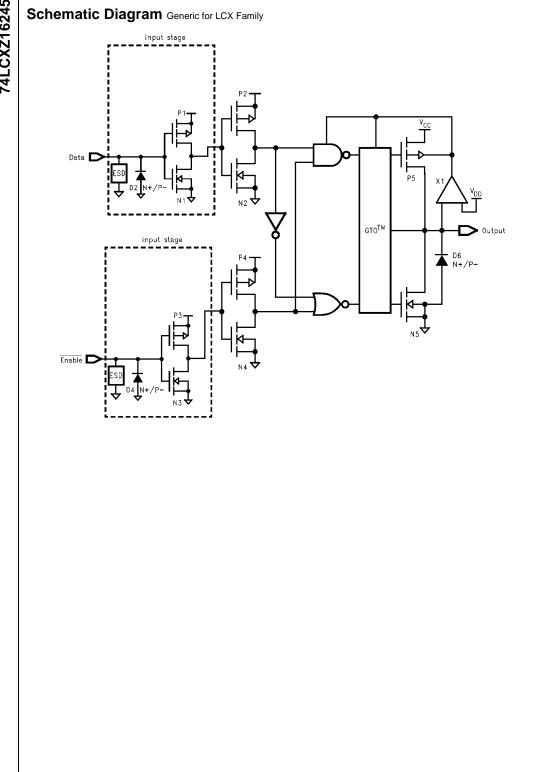


FIGURE 2. Waveforms (Input Characteristics; f =1MHz, $t_r = t_f = 3ns$)

Symbol	V _{cc}		
Cymbol	3.3V ± 0.3V	2.7V	
V _{mi}	1.5V	1.5V	
V _{mo}	1.5V	1.5V	
V _x	V _{OL} + 0.3V	V _{OL} + 0.3V	
V _y	V _{OH} – 0.3V	V _{OH} – 0.3V	



Physical Dimensions inches (millimeters) unless otherwise noted 12 50±0 10: -B-8 9.20 B.10 4.05 O.2 C B A ALL LEAD TIPS PIN #1 IDENT 0.50 LAND PATTERN RECOMMENDATION □ 0.1 C SEE DETAIL A 0.90+0.15 0.09-0.20 0.10±0.05 0.50 0.17-0.27 ♦ 0.13\(\oldsymbol{\text{0}} \) A B\(\oldsymbol{\text{S}} \) C\(\oldsymbol{\text{S}} \) 12.00' TOP & BOTTOM R0.16 DIMENSIONS ARE IN MILLIMETERS CAGE PLANE R0.31 0.25 NOTES: A CONFORMS TO JEDEC REGISTRATION MC-153, VARIATION ED, DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A MTD48REVC

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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